

# [CHIP PACKAGE STRUCTURE]

## Abstract of Disclosure

A chip package structure with a guard circuit design. The individual wires of two pairs of ground wires are positioned on each side of a high frequency signal wire so that external interference is minimized during transmission, multiple ground contacts are provided and current routes are shortened. In the meantime, strength of the electromagnetic field produced by the high frequency signal wire during transmission is limited within the pairs of ground wires. Ultimately, the range of interference by the electromagnetic field, the insertion loss and the return loss are all reduced resulting in improved performance of the chip package.

## Figures